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RF360 Europe GmbH

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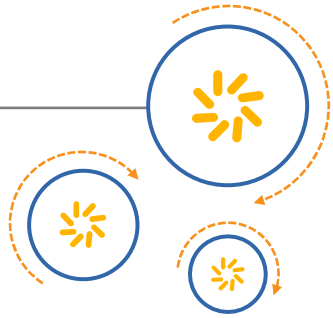

SAW components

SAW duplexer

Small cell & femtocell
LTE band 12

Series/type:	B8012
Ordering code:	B39741B8012P810
Date:	January 18, 2018
Version:	2.1

RF360 products mentioned within this document are offered by RF360 Europe GmbH and other subsidiaries of RF360 Holdings Singapore Pte. Ltd. (collectively, the “RF360 Subsidiaries”).

RF360 Holdings Singapore Pte. Ltd. is a joint venture of Qualcomm Global Trading Pte. Ltd. and EPCOS AG.

RF360 Europe GmbH, Anzinger Str. 13, München, Germany

SAW components **B8012**

SAW duplexer **707.5 / 737.5 MHz**

Data sheet

Table of contents

1 Application

- Low-loss SAW duplexer for LTE small cell & femtocell systems (Band 12)
- Usable pass band 17 MHz
- Low insertion attenuation
- Low amplitude ripple
- Rx = uplink = 699 – 716 MHz
- Tx = downlink = 729 – 746 MHz

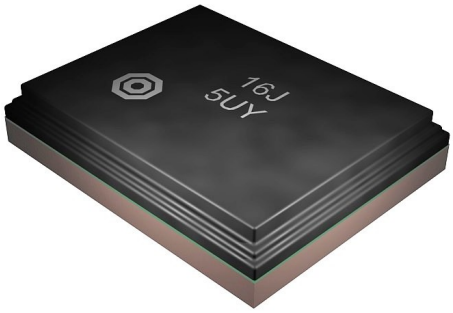

Figure 1: Picture of component with example of product marking.

2 Features

- Industrial grade qualified family
- Package size 2.5±0.1 mm × 2.0±0.1 mm
- Package height 0.5 mm (max.)
- Approximate weight 0.01 g
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 2a (MSL2a)

3 Package

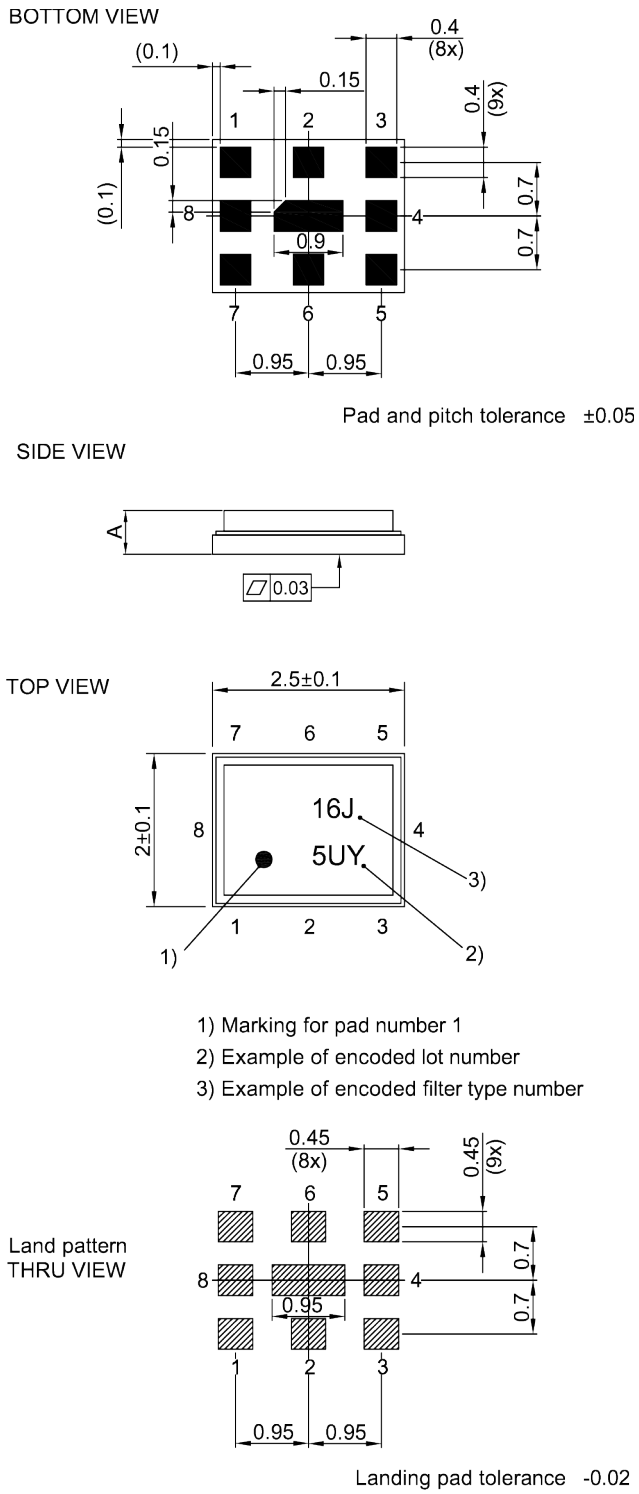

Figure 2: Drawing of package with package height A = 0.5 mm (max.). See Sec. Package information (p. 25).

4 Pin configuration

- 1 TX
- 3 RX
- 6 ANT
- 2, 4, 5, 7, 8, 9 Ground

5 Matching circuit

■ L_{p6} = 17 nH

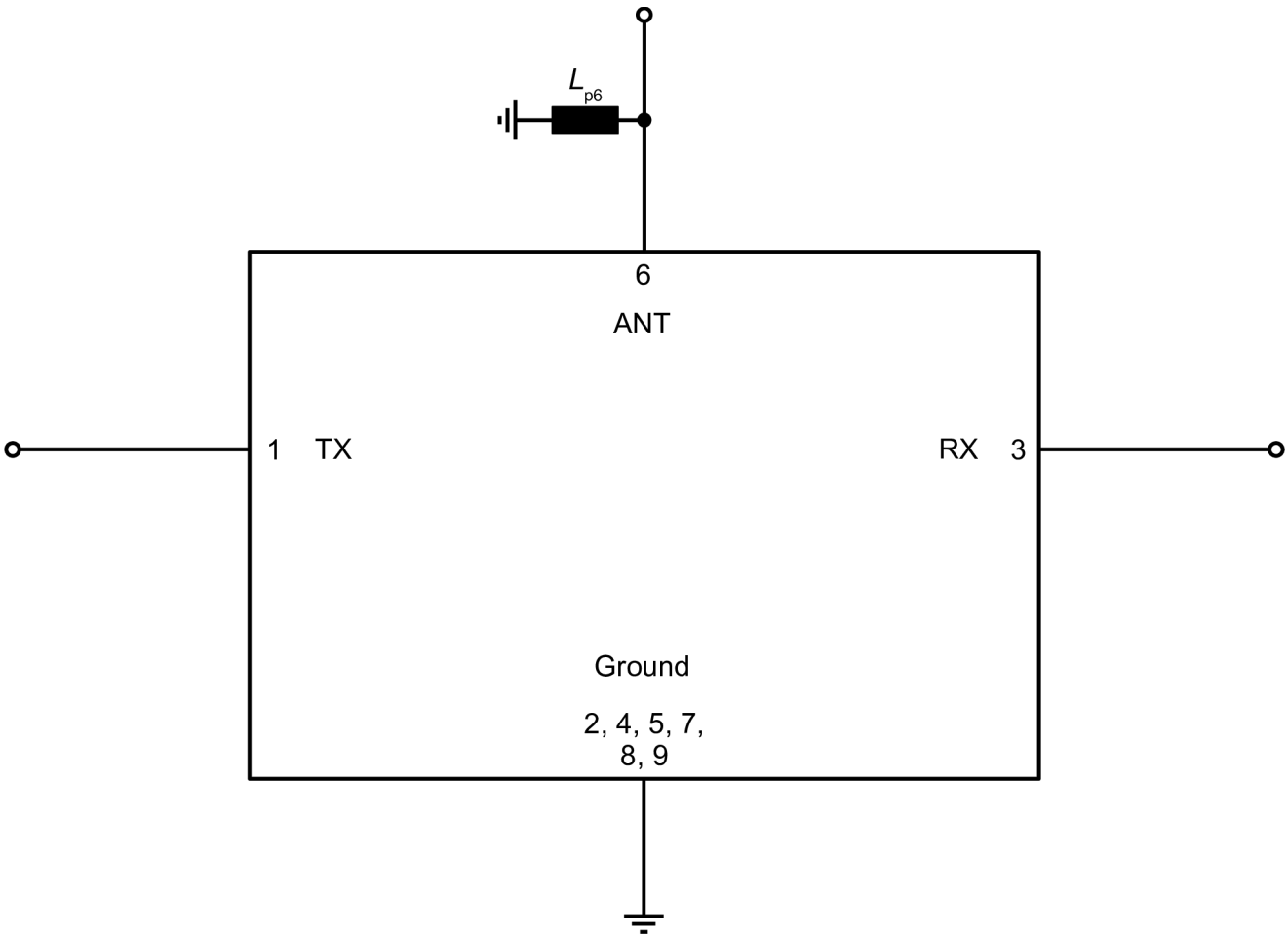

Figure 3: Schematic of matching circuit.

6 Characteristics

6.1 TX – ANT

Temperature range for specification T_{SPEC} = −10 °C ... +85 °C
TX terminating impedance Z_{TX} = 50 Ω
ANT terminating impedance Z_{ANT} = 50 Ω with par. 17 nH[1)]
RX terminating impedance Z_{RX} = 50 Ω

Characteristics TX – ANT				min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Center frequency			f_C	—	737.5	—	MHz
Maximum insertion attenuation			α_{max}				
	729... 746	MHz		—	1.8	2.5	dB
Amplitude ripple (p-p)			Δα				
	729... 746	MHz		—	0.6	1.3	dB
Maximum VSWR			$VSWR_{max}$				
@ TX port	729... 746	MHz		—	1.8	2.0	
@ ANT port	729... 746	MHz		—	1.6	2.0	
Maximum error vector magnitude			EVM_{max} [2)]				
	731.5... 743.5	MHz		—	2.5	4.0	%
Minimum attenuation			α_{min}				
	10... 699	MHz		30	42	—	dB
	699... 716	MHz		45	51	—	dB
	777... 787	MHz		35	48	—	dB
	788... 798	MHz		35	45	—	dB
	824... 849	MHz		35	41	—	dB
	869... 894	MHz		35	40	—	dB
	1398... 1432	MHz		35	45	—	dB
	1458... 1492	MHz		35	46	—	dB
	1574... 1606	MHz		35	47	—	dB
	1710... 1755	MHz		35	49	—	dB
	1850... 1915	MHz		40	49	—	dB
	1930... 1995	MHz		40	49	—	dB
	2097... 2148	MHz		30	46	—	dB
	2110... 2170	MHz		30	46	—	dB
	2187... 2238	MHz		30	44	—	dB
	2400... 2500	MHz		35	42	—	dB

1) See Sec. Matching circuit (p. 6).
2) Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.

6.2 ANT – RX

Temperature range for specification	T_{SPEC}	= −10 °C ... +85 °C
TX terminating impedance	Z_{TX}	= 50 Ω
ANT terminating impedance	Z_{ANT}	= 50 Ω with par. 17 nH[1)]
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics ANT – RX				**min.** for T_{SPEC}	**typ.** @ +25 °C	**max.** for T_{SPEC}	
Center frequency			f_C	—	707.5	—	MHz
Maximum insertion attenuation			α_{max}				
	699... 714.75	MHz		—	2.3	3.0	dB
	714.75... 716	MHz		—	2.4	4.5	dB
Amplitude ripple (p-p)			Δα				
	699... 714.75	MHz		—	0.9	2.0	dB
	699... 716	MHz		—	1.0	3.0	dB
Maximum VSWR			$VSWR_{max}$				
@ ANT port	699... 716	MHz		—	1.8	2.2	
@ RX port	699... 716	MHz		—	2.0	2.3	
Maximum error vector magnitude			EVM_{max} [2)]				
	701.5... 713.5	MHz		—	2.2	5.0	%
Minimum attenuation			α_{min}				
	100... 600	MHz		45	58	—	dB
	693.25... 694	MHz		12	15	—	dB
	694... 694.5	MHz		5	23	—	dB
	694.5... 697.75	MHz		1.5	2.5	—	dB
	716... 721	MHz		1	2.3	—	dB
	721... 722.5	MHz		5	13	—	dB
	722.5... 728	MHz		10	19	—	dB
	729... 746	MHz		45	50	—	dB
	746... 756	MHz		42	48	—	dB
	758... 768	MHz		45	49	—	dB
	777... 787	MHz		45	50	—	dB
	788... 798	MHz		45	52	—	dB
	869... 894	MHz		45	54	—	dB
	1398... 1432	MHz		45	56	—	dB
	1574... 1606	MHz		45	54	—	dB
	1710... 1755	MHz		45	53	—	dB
	1850... 1915	MHz		40	51	—	dB
	1930... 1995	MHz		40	50	—	dB
	2110... 2170	MHz		30	44	—	dB
	2400... 2500	MHz		40	50	—	dB

1) See Sec. Matching circuit (p. 6).

2) Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.

6.3 TX – RX

Temperature range for specification	T_{SPEC}	= −10 °C ... +85 °C
TX terminating impedance	Z_{TX}	= 50 Ω
ANT terminating impedance	Z_{ANT}	= 50 Ω with par. 17 nH[1)]
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics TX – RX				**min.** for T_{SPEC}	**typ.** @ +25 °C	**max.** for T_{SPEC}	
Minimum isolation			α_{min}				
	699... 716	MHz		48	52	—	dB
	729... 746	MHz		48	52	—	dB

1) See Sec. Matching circuit (p. 6).

7 Maximum ratings

Operable temperature	T_{OP} = −40 °C ... +95 °C	
Storage temperature	T_{STG} [1] = −40 °C ... +95 °C	
DC voltage	$\|V_{DC}\|$ [2] = 0 V	
ESD voltage		
	V_{ESD} [3] = 50 V	Machine model.
	V_{ESD} [4] = 100 V	Human body model.
Input power	P_{IN}	
@ TX port: 729 ... 746 MHz	31 dBm[5]	5 MHz LTE downlink signal (25 RB) for 50000 h @ 55 °C. P_{IN} 31 dBm average – 42 dBm peak. Source and load impedance 50Ω.
@ TX port: other frequency ranges	10 dBm	Source and load impedance 50Ω.

1) Not valid for packaging material. Storage temperature for packaging material is −25 °C to +40 °C.
2) In case of applied DC voltage blocking capacitors are mandatory.
3) According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses.
4) According to JESD22-A114F (HBM – Human Body Model), 1 negative & 1 positive pulse.
5) Expected lifetime according to power durability tests, and wear out models.

8 Transmission coefficients

8.1 TX – ANT

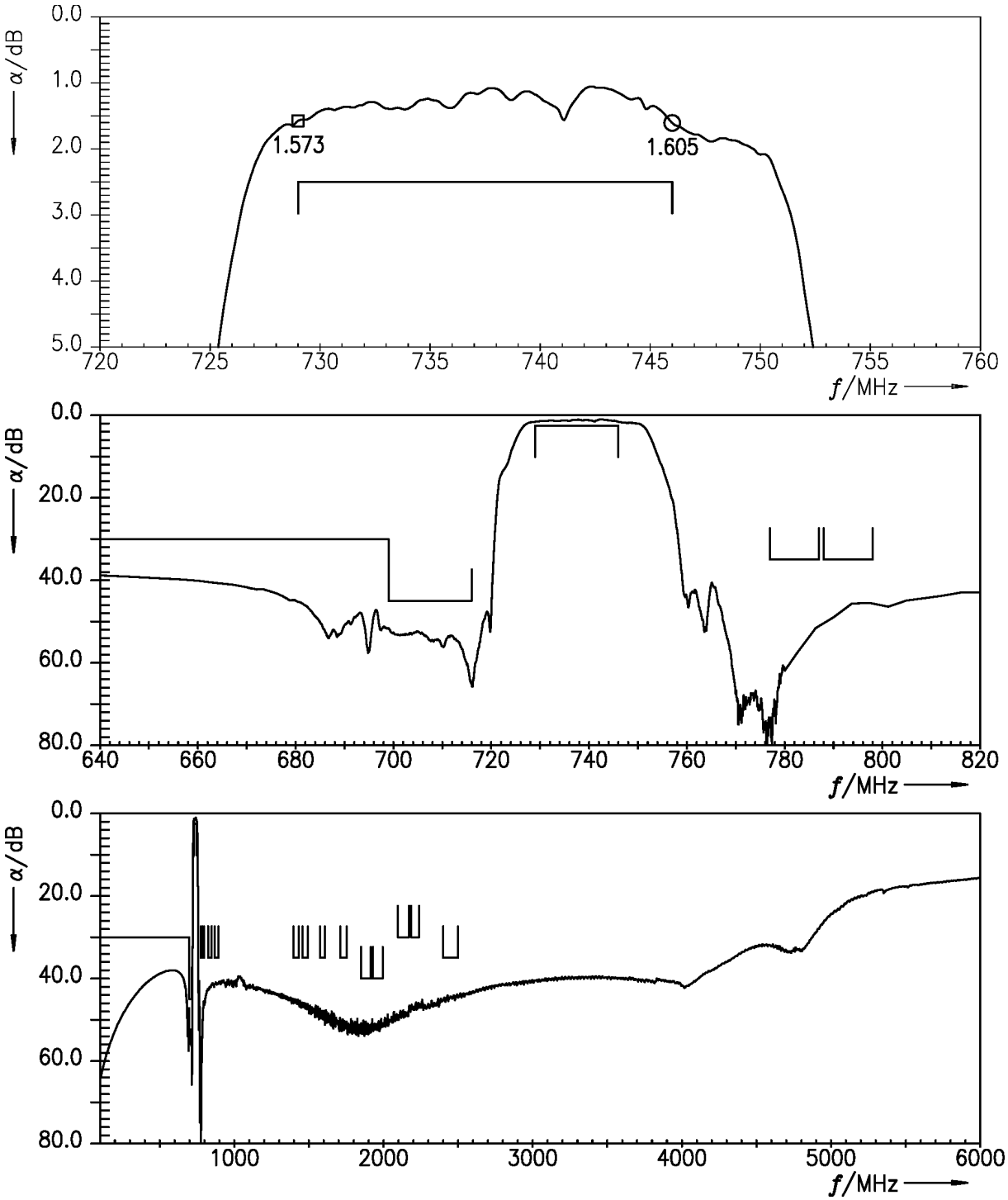

Figure 4: Attenuation TX – ANT.

8.2 ANT – RX

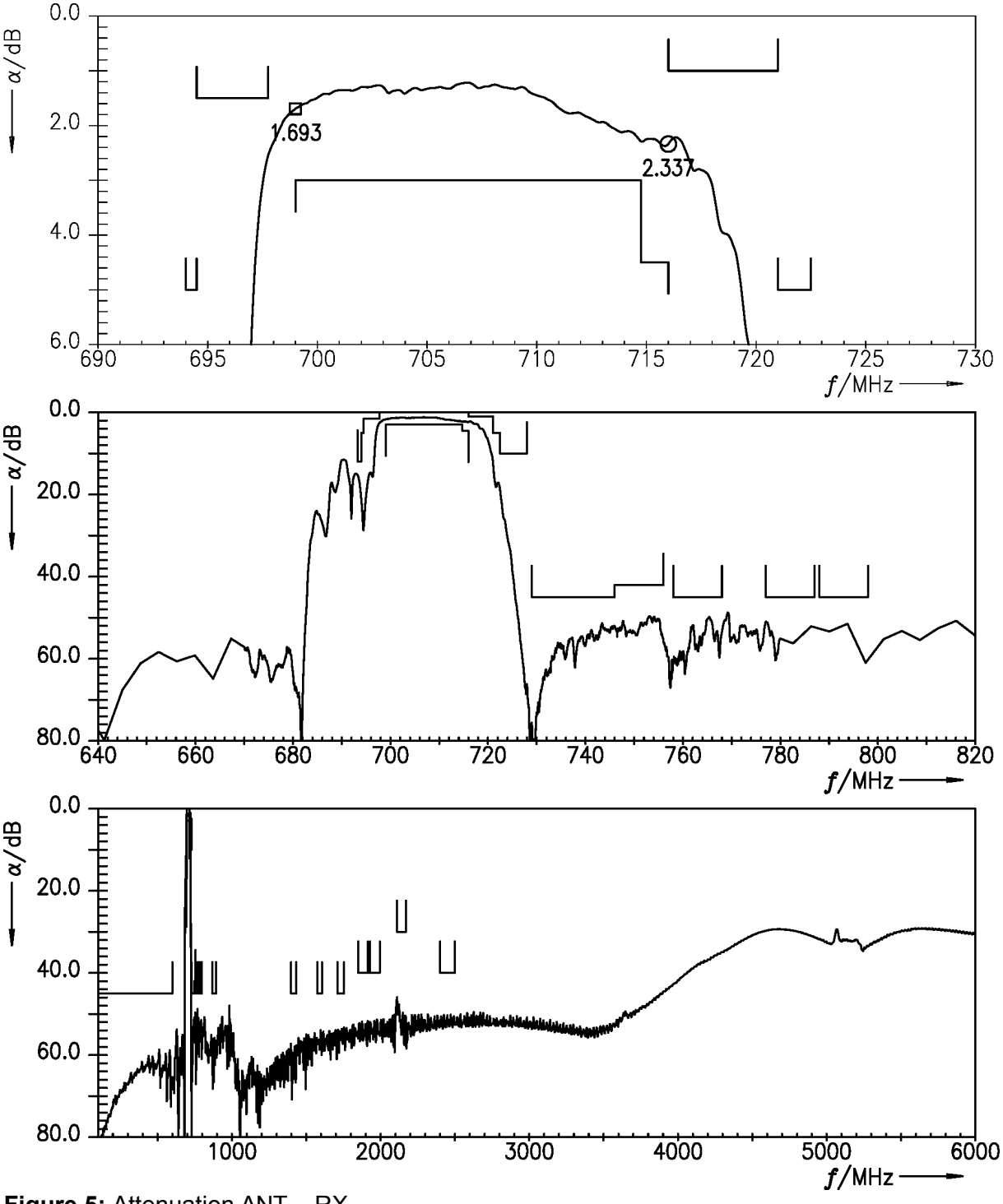

Figure 5: Attenuation ANT – RX.

8.3 TX – RX

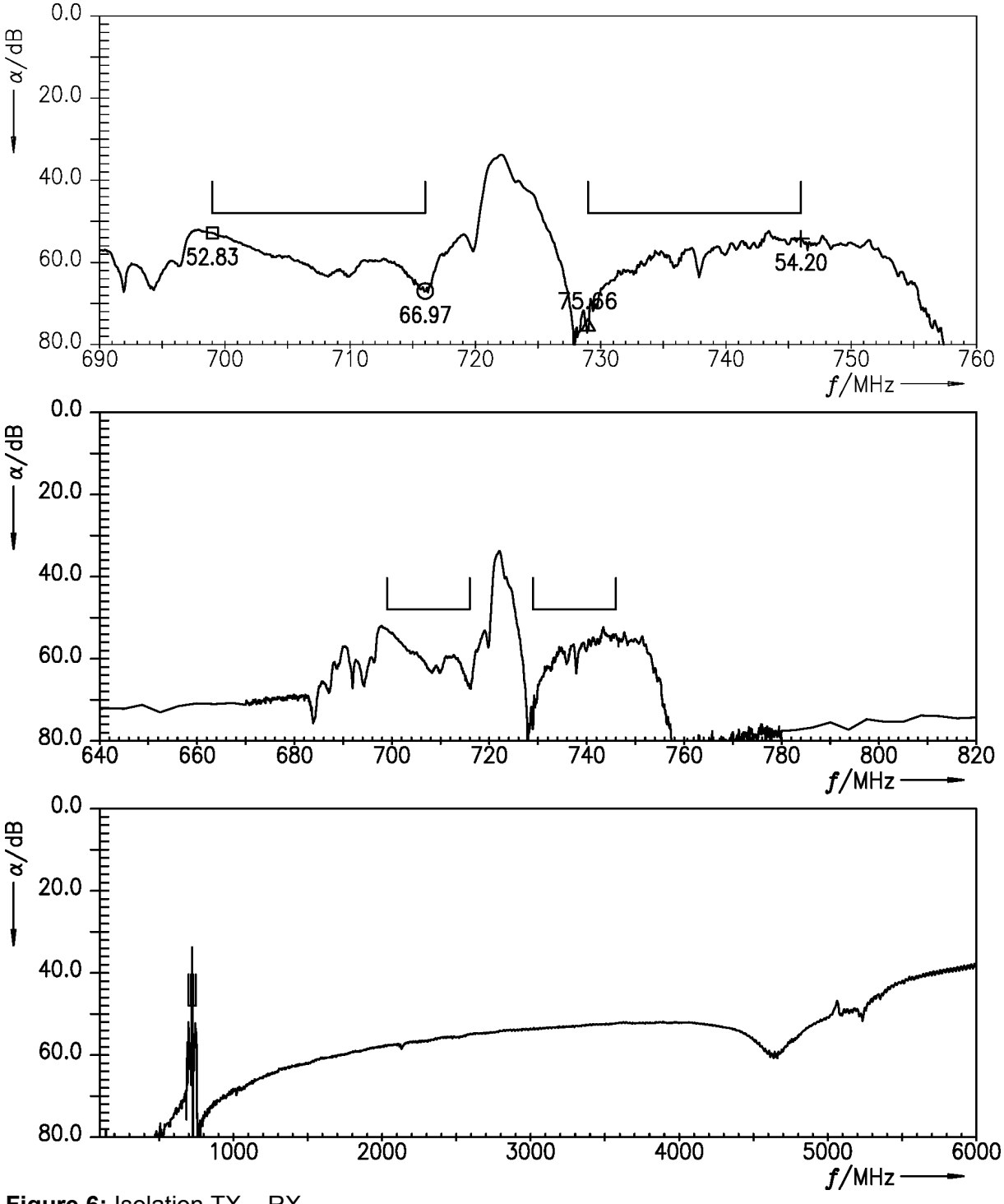

Figure 6: Isolation TX – RX.

9 Reflection coefficients

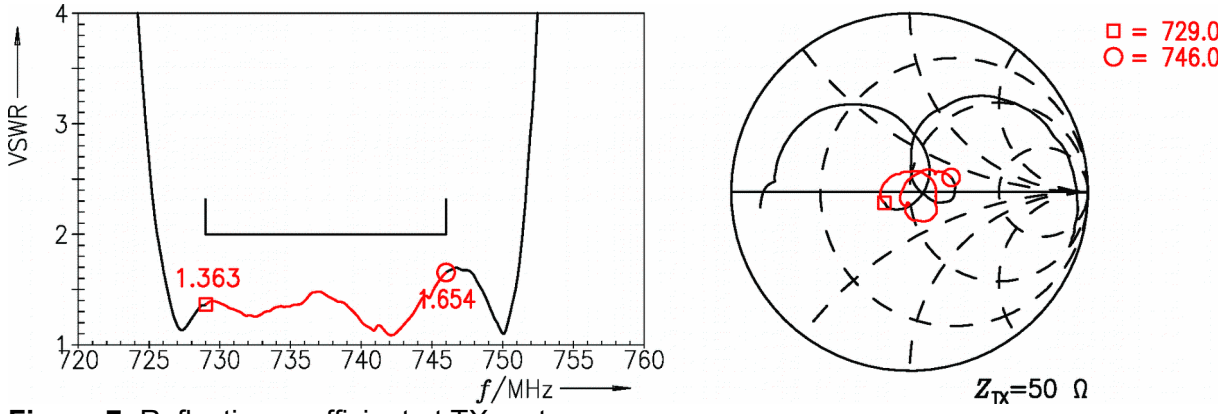

Figure 7: Reflection coefficient at TX port.

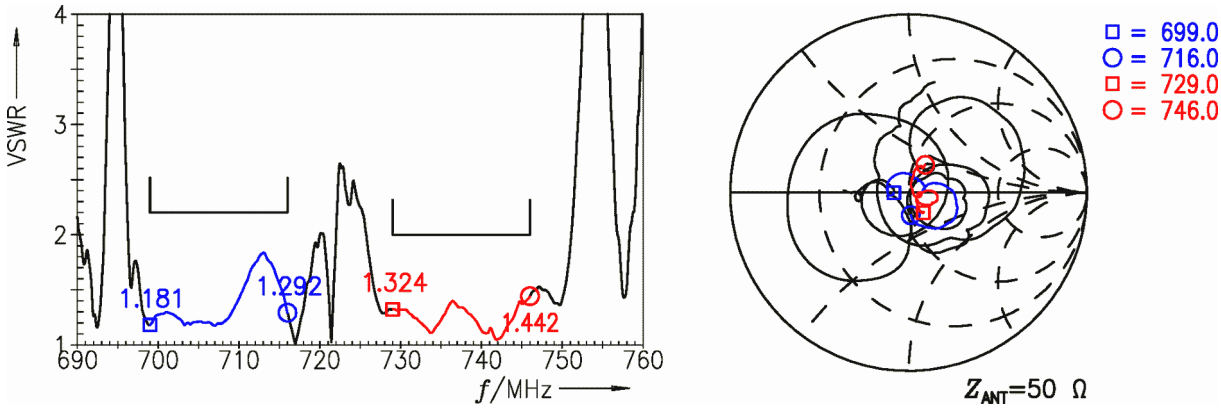

Figure 8: Reflection coefficient at ANT port.

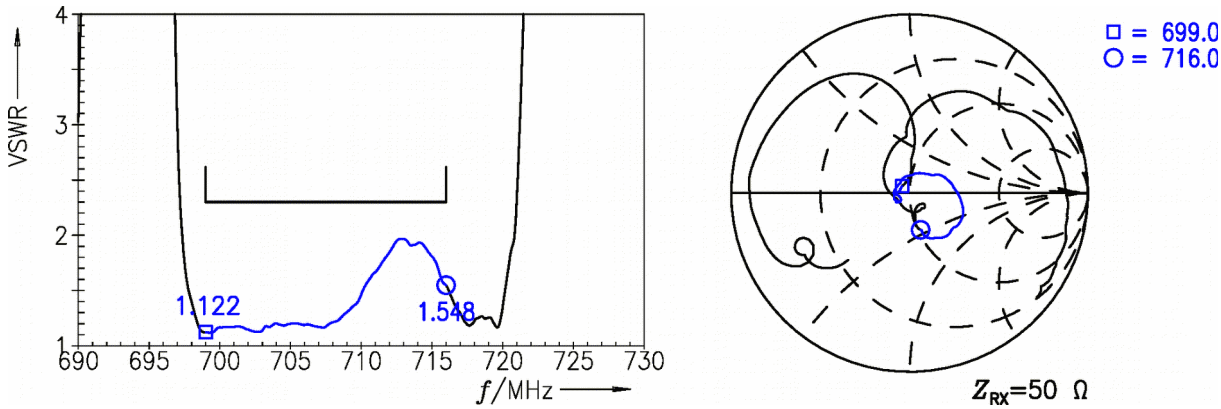

Figure 9: Reflection coefficient at RX port.

10 EVMs

10.1 TX – ANT

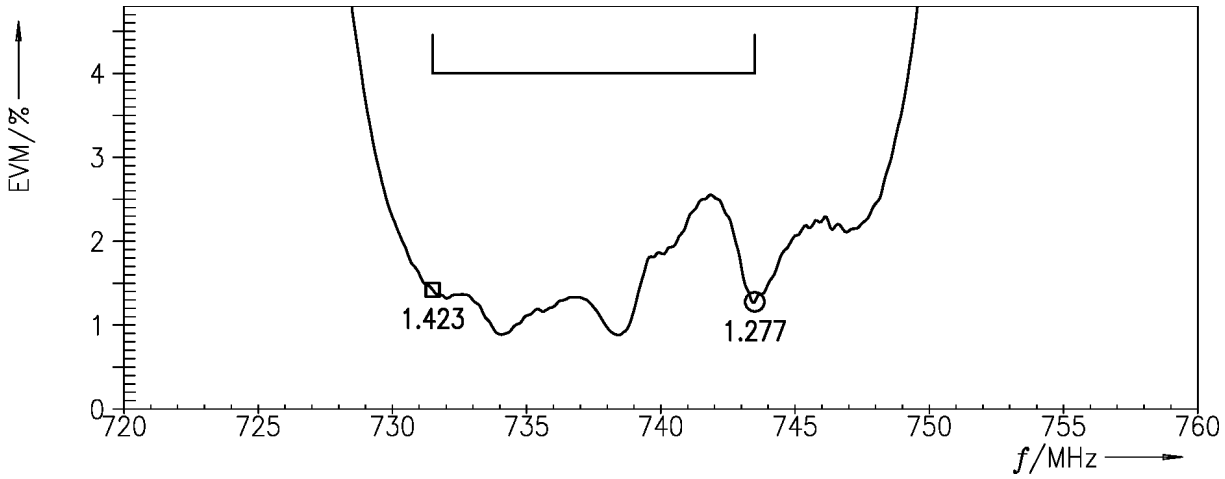

Figure 10: Error vector magnitude TX – ANT.

10.2 ANT – RX

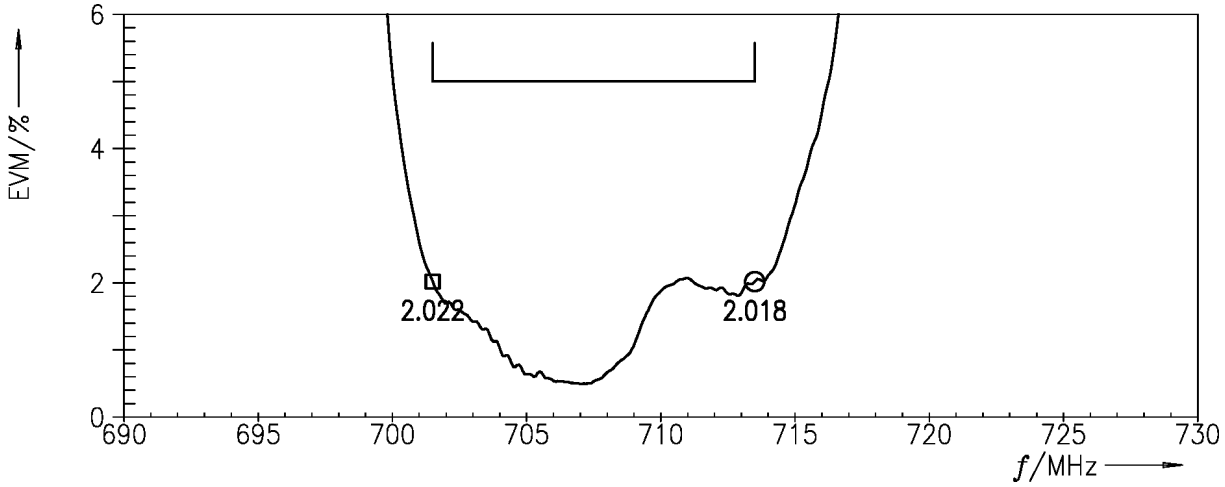

Figure 11: Error vector magnitude ANT – RX.

11 Packing material

11.1 Tape

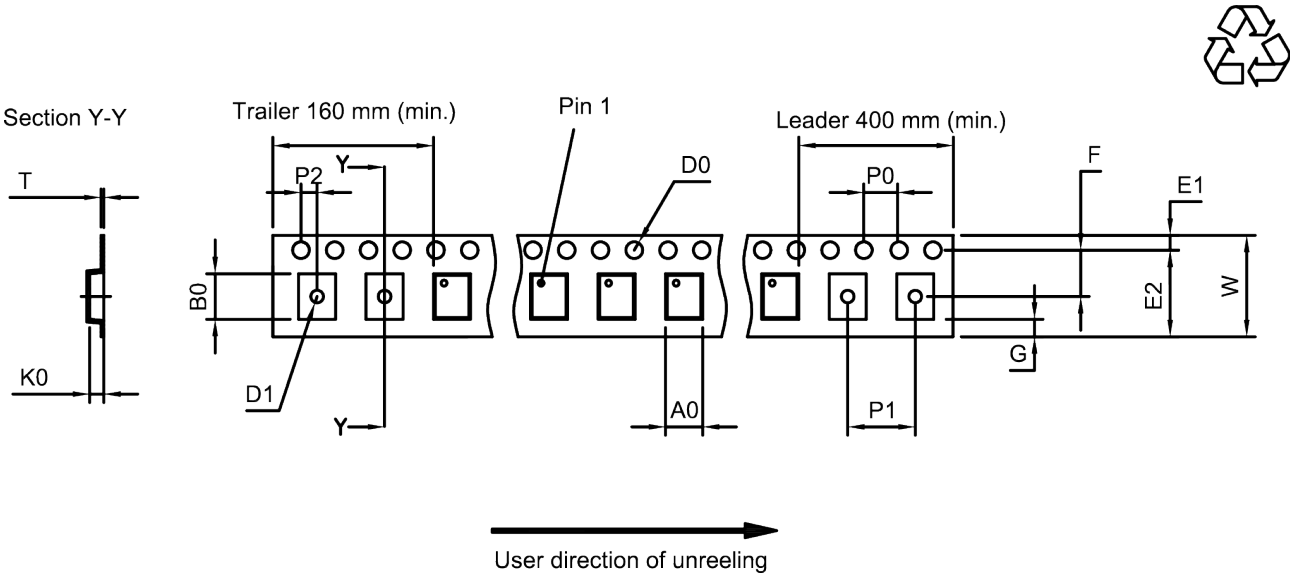

Figure 12: Drawing of tape (first-angle projection) with tape dimensions according to Table 1.

A_0	2.25±0.05 mm
B_0	2.75±0.05 mm
D_0	1.5+0.1/−0 mm
D_1	1.0 mm (min.)
E_1	1.75±0.1 mm

E_2	6.25 mm (min.)
F	3.5±0.05 mm
G	0.75 mm (min.)
K_0	0.6±0.05 mm
P_0	4.0±0.1 mm

P_1	4.0±0.1 mm
P_2	2.0±0.05 mm
T	0.25±0.03 mm
W	8.0+0.3/−0.1 mm

Table 1: Tape dimensions.

11.2 Reel with diameter of 180 mm

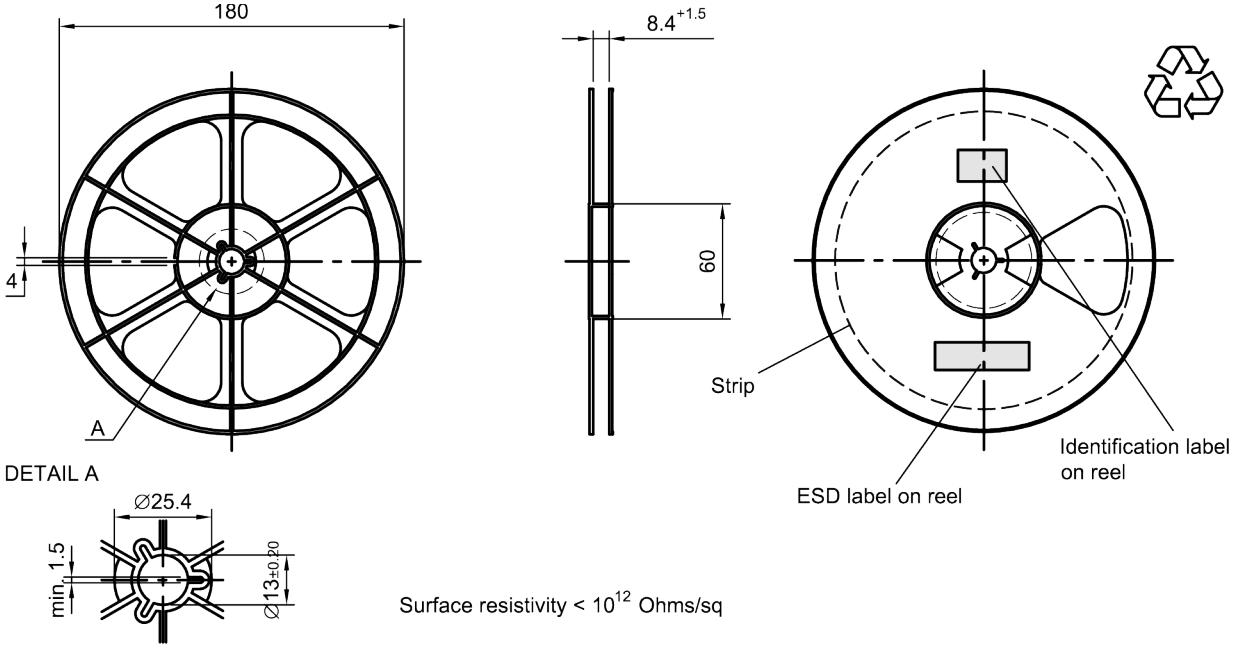

Figure 13: Drawing of reel (first-angle projection) with diameter of 180 mm.

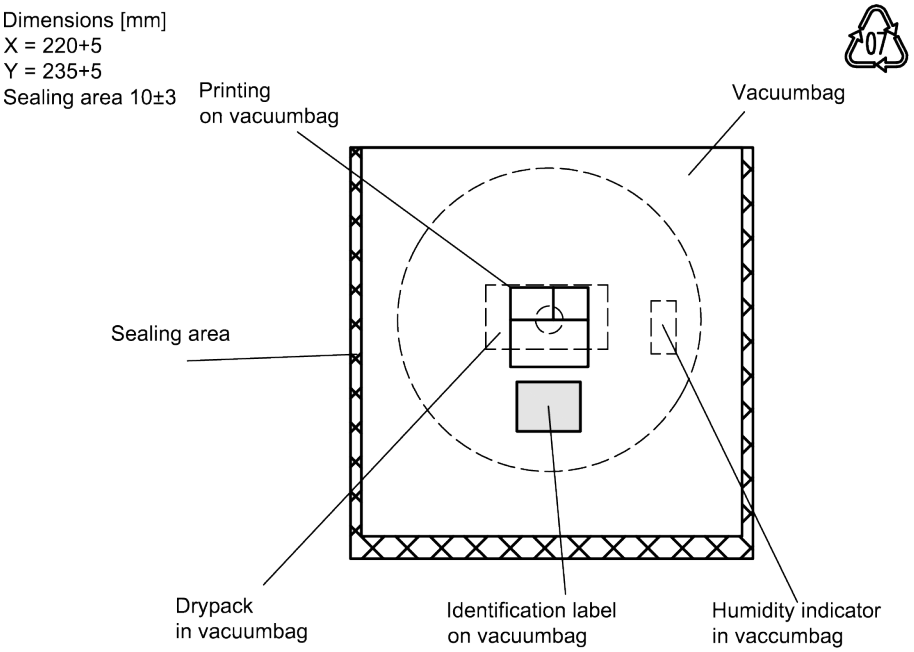

Figure 14: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

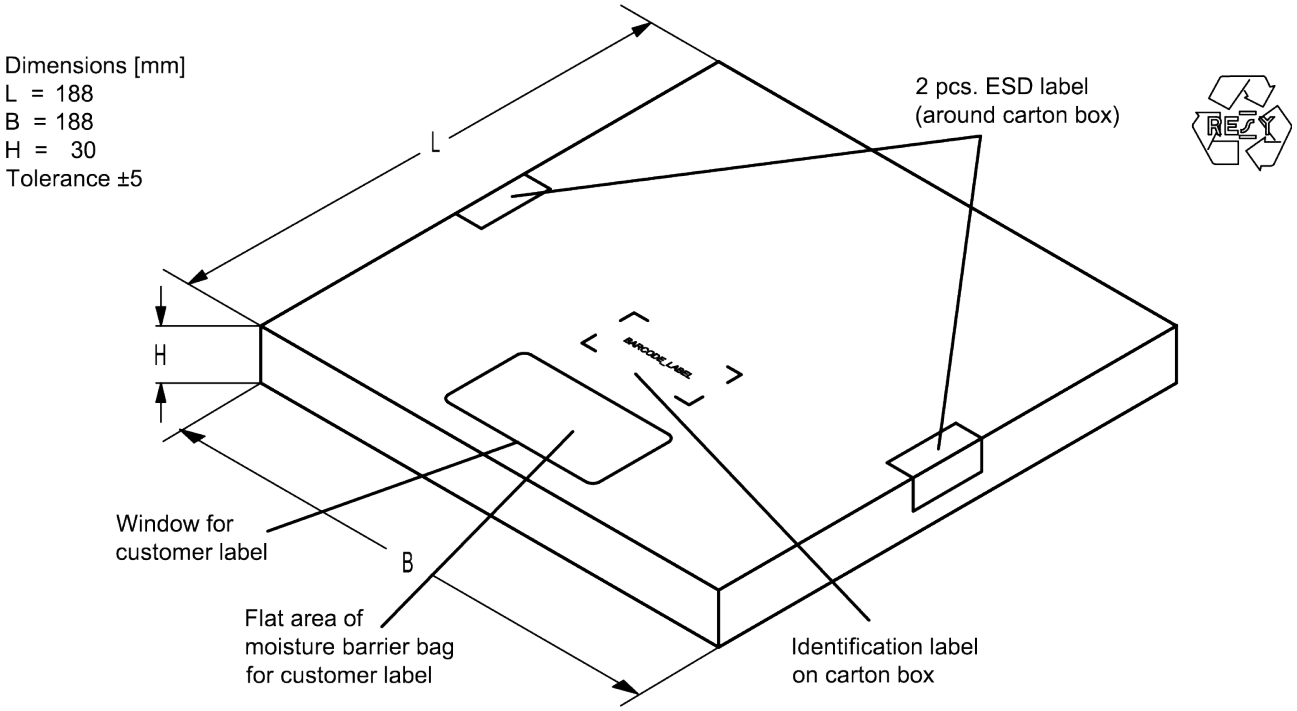

Figure 15: Drawing of folding box for reel with diameter of 180 mm.

11.3 Reel with diameter of 330 mm

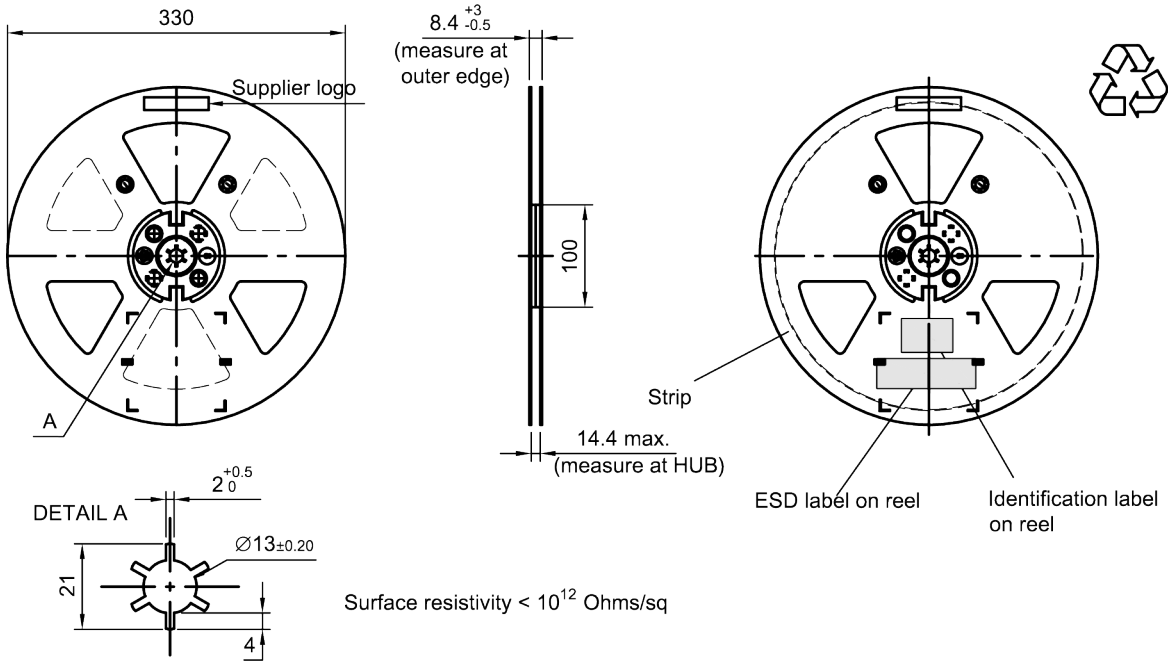

Figure 16: Drawing of reel (first-angle projection) with diameter of 330 mm.

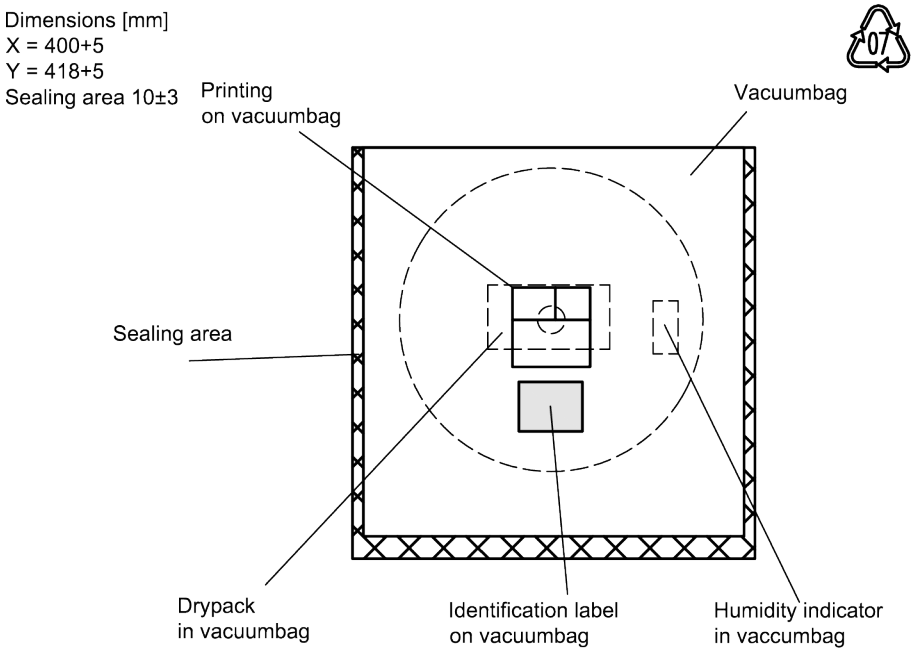

Figure 17: Drawing of moisture barrier bag (MBB) for reel with diameter of 330 mm.

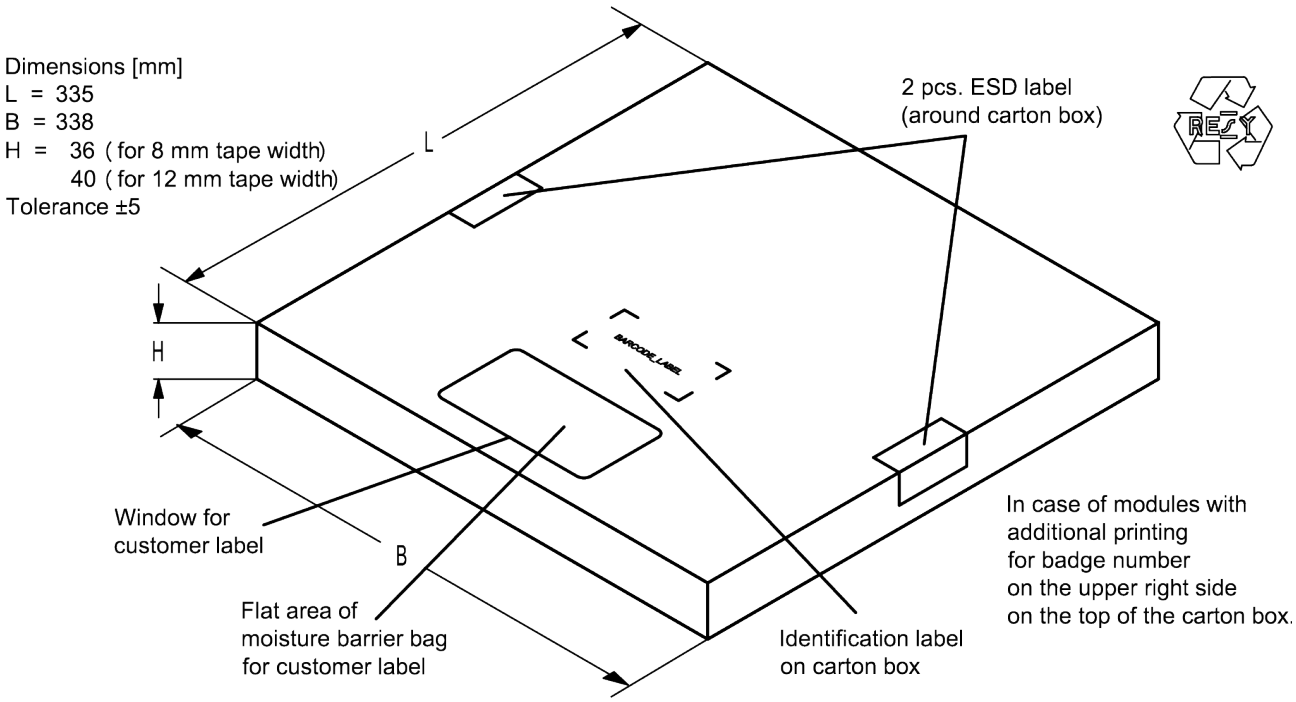

Figure 18: Drawing of folding box for reel with diameter of 330 mm.

12 Marking

Products are marked with product type number and lot number encoded according to Table 2:

- Type number:

  The 4 digit type number of the ordering code, e.g., B3xxxxB**1234**xxxx,
  is encoded by a special BASE32 code into a 3 digit marking.

  Example of decoding type number marking on device in decimal code.
  16J **=>** **1234**
  1 x 32^2 + **6** x 32^1 + **18 (=J)** x 32^0 **=** **1234**
  The BASE32 code for product type B8012 is 7TC.

- Lot number:

  The last 5 digits of the lot number, e.g., **12345**,
  are encoded based on a special BASE47 code into a 3 digit marking.

  Example of decoding lot number marking on device in decimal code.
  5UY **=>** **12345**
  5 x 47^2 + **27 (=U)** x 47^1 + **31 (=Y)** x 47^0 **=** **12345**

Adopted BASE32 code for type number			
Decimal value	Base32 code	Decimal value	Base32 code
0	0	16	G
1	1	17	H
2	2	18	J
3	3	19	K
4	4	20	M
5	5	21	N
6	6	22	P
7	7	23	Q
8	8	24	R
9	9	25	S
10	A	26	T
11	B	27	V
12	C	28	W
13	D	29	X
14	E	30	Y
15	F	31	Z

Adopted BASE47 code for lot number			
Decimal value	Base47 code	Decimal value	Base47 code
0	0	24	R
1	1	25	S
2	2	26	T
3	3	27	U
4	4	28	V
5	5	29	W
6	6	30	X
7	7	31	Y
8	8	32	Z
9	9	33	b
10	A	34	d
11	B	35	f
12	C	36	h
13	D	37	n
14	E	38	r
15	F	39	t
16	G	40	v
17	H	41	\
18	J	42	?
19	K	43	{
20	L	44	}
21	M	45	<
22	N	46	>
23	P		

Table 2: Lists for encoding and decoding of marking.

13 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
T > 220 °C	30 s to 70 s
T > 230 °C	min. 10 s
T > 245 °C	max. 20 s
T ≥ 255 °C	–
peak temperature T_{peak}	250 °C +0/-5 °C
wetting temperature T_{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

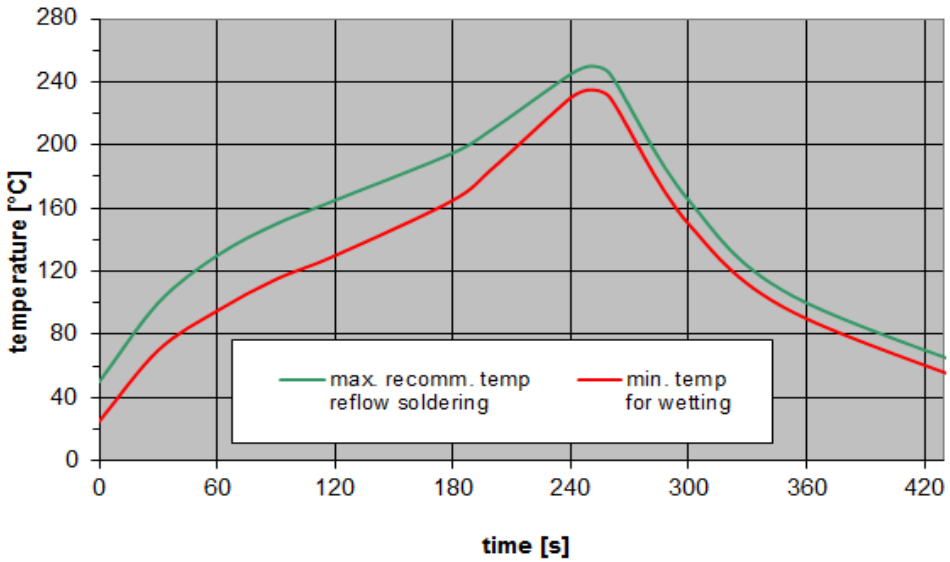

Figure 19: Recommended reflow profile for convection and infrared soldering – lead-free solder.

14 Annotations

14.1 Matching coils

See TDK inductor pdf-catalog http://www.tdk.co.jp/tefe02/coil.htm#aname1 and Data Library for circuit simulation http://www.tdk.co.jp/etvcl/index.htm.

14.2 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

14.3 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

14.4 Ordering codes and packing units

Ordering code	Packing unit
B39741B8012P810	5000 pcs

Table 4: Ordering codes and packing units.

15 Cautions and warnings

15.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under www.rf360jv.com/orderingcodes.

15.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

15.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

15.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Dimensions do not include burrs.

Projection method

Unless otherwise specified first-angle projection is applied.